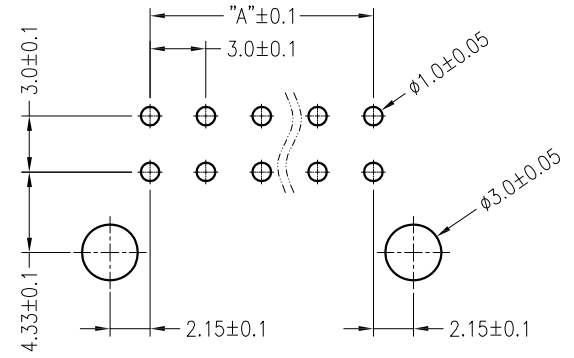
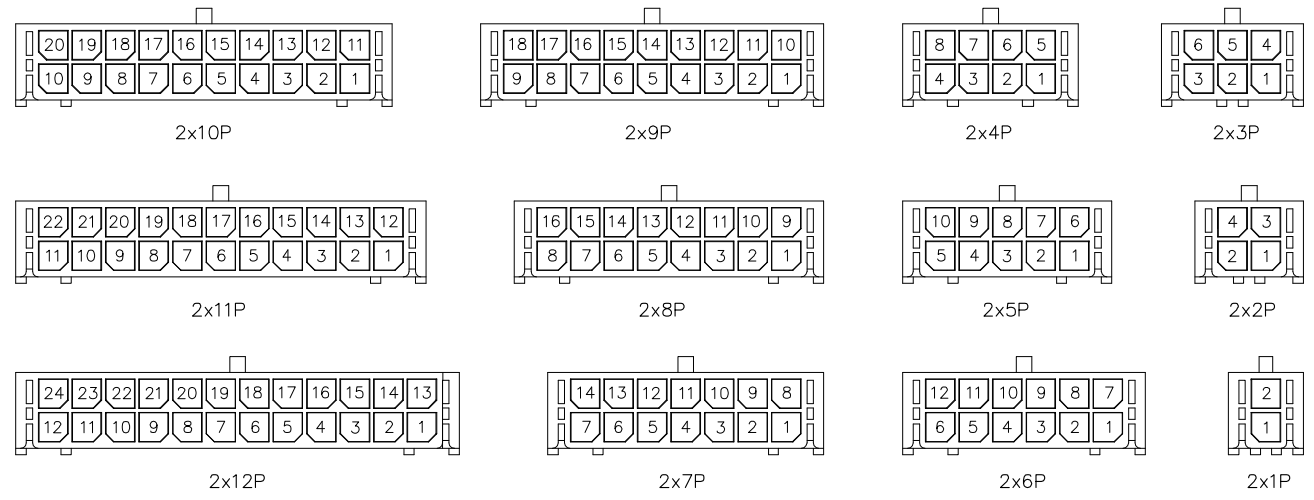


	1	2	3	4	5	6	7	8		
A	Poles	DIM.A	DIM.B						SPECIFICATION:	
	2x1P	-	6.65							
	2x2P	3.00	9.65							
	2x3P	6.00	12.65							
	2x4P	9.00	15.65							
	B	2x5P	12.00							18.65
		2x6P	15.00							21.65
		2x7P	18.00							24.65
	C	2x8P	21.00							27.65
		2x9P	24.00							30.65
		2x10P	27.00							33.65
	D	2x11P	30.00							36.65
2x12P		33.00	39.65							

- Voltage rating:
AC, DC, 250V(rms)
- Current rating:
5A AWG #20
- Withstand voltage:
1000V AC/minute
- Working Temperature:
-40°C~ +105°C
- Insulation resistance:
≥ 1000M Ω
- Contact resistance:
≤ 40m Ω
- Terminal mtr'l:
BRASS
- Material:
Housing-PA9T,UL94V-0
- Applicable Wire:
AWG #24~ AWG #20

RoHS
Compliant

CIRCUIT SIZE LAYOUT



RECOMMENDED PCB LAYOUT

Ordering Information

WJ - 1 - XX - PT - 3003-1-44

3.0P Wafer Solder/PCB Total PIN Contact Plated Packaging
1:DIP RA 1: Bag
2:DIP VT
3:SMT RA
4:SMT VT

REV.	REVISION RECORD	DATE	General Tolerances	
A	Original	07/25/17	LINEAR 0.0 ±0.35 0.00±0.20	ANGLES ±3°
			UNIT: mm	
			A4	NAME DATE
			APPROVED	WENDY
			DESIGNER	WHITE
			DRAWN	JINDAY



TITLE: 3.0P Wafer DIP Right Angle
Dual Rows with boardlock

DWG.NO.: WJ1XXPT30031-44 REV. A

SCALE 1 : 1 SHEET 1 OF 1